# **inter<sub>sil</sub>**

# Digital Red, Green and Blue Color Light Sensor with IR Blocking Filter

# ISL29125

The ISL29125 is a low power, high sensitivity, RED, GREEN, and BLUE color light sensor (RGB) with an I<sup>2</sup>C (SMBus compatible) interface. Its state-of-the-art photodiode array provides an accurate RGB spectral response and excellent light source to light source variation (LS2LS). The ISL29125 is designed to reject IR in light sources allowing the device to operate in environments from sunlight to dark rooms. The integrating ADC rejects 50Hz and 60Hz flicker caused by artificial light sources. A selectable range allows the user to optimize sensitivity suitable for the specific application. In normal operation mode the device consumes 56µA which reduces to 0.5µA in power down mode. The ISL29125 supports hardware and software user programmable interrupt thresholds. The Interrupt persistency feature reduces false trigger notification. The device operates on supplies (VDD) from 2.25V to 3.63V, I<sup>2</sup>C supply from 1.7V to 3.63V, and operating temperature over the -40°C to +85°C.

# **Features**

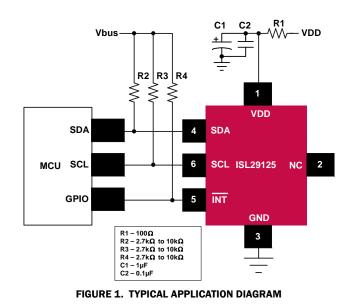
- 56µA operating current, 0.5µA shutdown current
- Selectable range (Via I<sup>2</sup>C)
- I<sup>2</sup>C (SMBus compatible) output
- ADC resolution 16 bits
- Programmable interrupt windows
- Two optical sensitivity ranges
- Range 0 = 5.7m lux to 375 lux
- Range 1 = 0.152 lux to 10,000 lux
- Operating power supply 2.25 to 3.63V
- I<sup>2</sup>C power supply 1.7V to 3.63V
- 6 Ld ODFN (1.65x1.65x0.7mm) package

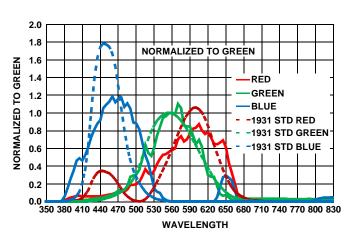
# **Applications**

- Smart phone, PDA, GPS, tablet PCs, LCD-TVs, digital picture frames, digital cameras
- Dynamic display color balancing
- · Printer color enhancement
- · Industrial/commercial LED lighting color management
- Ambient light color detection/correction
- OLED display aging compensation

# **Related Literature**

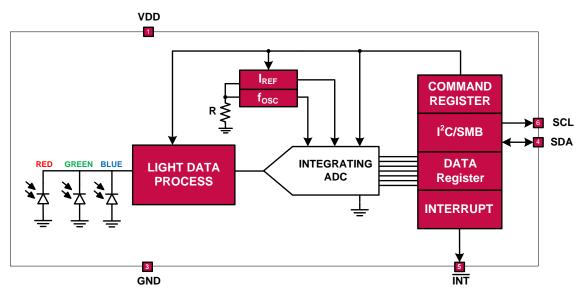
See <u>AN1914</u>, "Evaluation Hardware/Software User Manual for RGB Sensor"



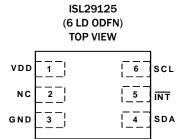


#### FIGURE 2. NORMALIZED SPECTRAL RESPONSE FOR RED, GREEN, AND BLUE SENSING

# **Block Diagram**



# **Pin Configuration**



# **Pin Descriptions**

PIN NUMBER	PIN NAME	DESCRIPTION
1	VDD	Positive supply
2	NC	No Connect
3	GND	Ground
4	SDA	I <sup>2</sup> C serial data
5	ĪNT	Interrupt; LOW for interrupt alarming. INT pin is open drain. INT remains asserted until the interrupt status bit is reset. INT also become a input when it is set in SYNC mode
6	SCL	I <sup>2</sup> C serial clock

# **Ordering Information**

PART NUMBER (Notes 1, 2, 3)			PKG. DWG. #	
ISL29125IR0Z-T7	-40 to +85	6 Ld ODFN	L6.1.65x1.65	
ISL29125EVAL1Z	Evaluation Board			

NOTES:

1. Please refer to TB347 for details on reel specifications.

2. These Intersil Pb-free plastic packaged products employ special Pb-free material sets; molding compounds/die attach materials and NiPdAu plate - e4 termination finish, which is RoHS compliant and compatible with both SnPb and Pb-free soldering operations. Intersil Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J STD-020.

3. For Moisture Sensitivity Level (MSL), please see product information page for ISL29125. For more information on MSL please see tech brief TB477.

#### **Absolute Maximum Ratings**

VDD to GND	V
I <sup>2</sup> C Bus (SCL, SDA) and INT Pin Voltage	٧
I <sup>2</sup> C Bus (SCL, SDA) and INT Pin Current	Α
Input Voltage Slew Rate (Max) 0.1V/µ	s
ESD Ratings	
Human Body Model (HBM)2.5k	V
Machine Model (MM) 300	V
Charged Device Model (CDM) 2k	V

### **Thermal Information**

Thermal Resistance (Typical)	$\theta_{JA}$ ( ° C/W)
6 Ld ODFN Package (Note 4)	260
Maximum Junction Temperature (TJ <sub>MAX</sub> )	+90°C
Storage Temperature Range	-40°C to +100°C
Operating Temperature	40°C to +85°C
Pb-Free Reflow Profile	see link below
http://www.intersil.com/pbfree/Pb-FreeReflow.asp	

CAUTION: Do not operate at or near the maximum ratings listed for extended periods of time. Exposure to such conditions may adversely impact product reliability and result in failures not covered by warranty.

#### NOTE:

4. θ<sub>JA</sub> is measured in free air with the component mounted on a high effective thermal conductivity test board with "direct attach" features. See Tech Brief <u>TB379</u>.

#### **Electrical Specifications** $V_{DD} = 3.0V$ , $T_A = +25$ °C, 16-bit ADC operation, unless otherwise specified.

SYMBOL	PARAMETER	CONDITION	MIN (Note 6)	TYP	MAX (Note 6)	UNIT
V <sub>DD</sub>	Power Supply Range		2.25		3.63	v
I <sub>DD</sub>	Supply Current			56	85	μA
I <sub>DD1</sub>	Supply Current when Standby	Software disabled		29	37	μA
I <sub>DD2</sub>	Supply Current when Powered Down	Software disabled		0.5	1.45	μA
V <sub>I2C</sub>	Supply Voltage Range for I <sup>2</sup> C Interface		1.7		3.63	v
t <sub>INT</sub>	ADC Integration/Conversion Time	16-bit ADC data		101		ms
f <sub>I2C</sub>	I <sup>2</sup> C Clock Rate Range			500		kHz
D <sub>Dark</sub>	Count Output When Dark	Lux = 0 lux, Range = 0 (375lux)		1	5	Counts
ССТ	Corrected Color Temperature Accuracy	Illuminant A is at 300 lux (Note 11 and "References" on page 15 about CIE 1931, Planckian locus and standard illuminants)		±5		%
D <sub>FS</sub>	Full Scale ADC Code	ADC 16 bits			65535	Counts
		Green = 565nm		18		µW/cm2
	Fullscale on Range 0	Red = 620nm		20		µW/cm2
		Blue = 485nm		30		µW/cm2

NOTES:

5. 565nm Green, 620nm Red LED, 485nm Blue in white LED is used in production test. It's irradiance is calibrated to produce the same DATA count against an illuminance level of 130 lux fluorescent light.

6. Compliance to datasheet limits is assured by one or more methods: production test, characterization and/or design.

7. SDA and INT current sinking capability are guaranteed by design.

# **I<sup>2</sup>C Interface Specifications** $V_{DD} = 3.0V$ , $T_A = +25$ °C, 16-bit ADC operation, unless otherwise specified.

SYMBOL	PARAMETER	PARAMETER CONDITIONS				UNITS
VIL	SDA and SCL Input Buffer LOW Voltage				0.55	v
VIH	SDA and SCL Input Buffer HIGH Voltage		1.25			v
VHys (Note 8)	SDA and SCL Input Buffer Hysteresis			0.05xVDD		v
VOL (Note 8)	SDA Output Buffer LOW Voltage (open-drain), Sinking 4mA		0		0.4	v
CPIN (Note 8)	SDA and SCL Pin Capacitance	$T_A = +25 \degree C$ , f = 1MHz, $V_{DD} = 5V$ , $V_{IN} = 0V$ , $V_{OUT} = 0V$			10	pF
fSCL	SCL Frequency				500	kHz
t <sub>IN</sub>	Pulse Width Suppression Time at SDA and SCL Inputs	Any pulse narrower than the max spec is suppressed			50	ns
t <sub>AA</sub>	SCL Falling Edge to SDA Output Data Valid				900	ns
t <sub>BUF</sub>	Time the Bus Must be Free Before the Start of a New Transmission		1300			ns
t <sub>LOW</sub>	SCL LOW Time		1300			ns
t <sub>HIGH</sub>	SCL HIGH Time		600			ns
t <sub>SU:STA</sub>	START Condition Setup Time		600			ns
t <sub>HD:STA</sub>	START Condition Hold Time		600			ns
t <sub>SU:DAT</sub>	Input Data Setup Time		100			ns
t <sub>HD:DAT</sub>	Input Data Hold Time		30			ns
t <sub>SU:STO</sub>	STOP Condition Setup Time		600			ns
t <sub>HD:STHD:ST</sub>	STOP Condition Hold Time		600			ns
t <sub>HD:ST</sub>	Output Data Hold Time		0			ns
t <sub>HD:ST</sub> (Note 8)	SDA and SCL Rise Time		20+0.1xCb			ns
t <sub>HD:ST</sub> (Note 8)	SDA and SCL Fall Time		20+0.1xCb			ns
Cb (Note 8)	Capacitive Loading of SDA or SCL	Total on-chip and off-chip			400	pF
R <sub>PU</sub> (Note 8)	SDA and SCL Bus Pull-up Resistor Off-chip	Maximum is determined by t <sub>R</sub> and t <sub>F</sub> . For Cb = 400pF, max is about 2kΩ ~ 2.5kΩ. For Cb = 40pF, max is about 15kΩ ~ 20kΩ	1			kΩ

NOTES:

8. Limits should be considered typical and are not production tested.

9. These are I<sup>2</sup>C specific parameters and are not tested, however, they are used to set conditions for testing devices to validate specification.

10.  $C_b$  is the capacitance of the bus in pF.

# **SDA vs SCL Timing**

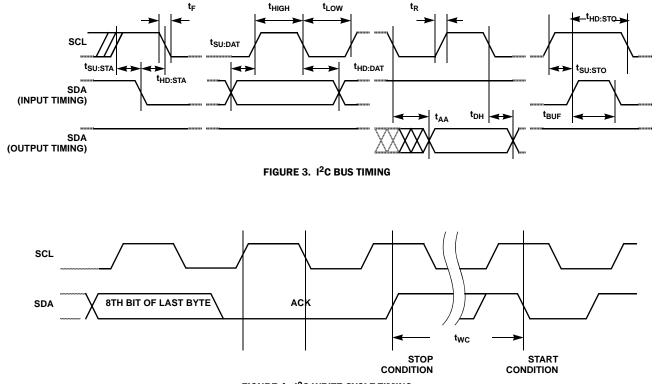
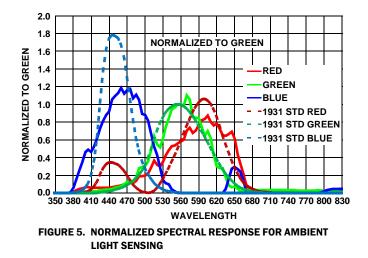
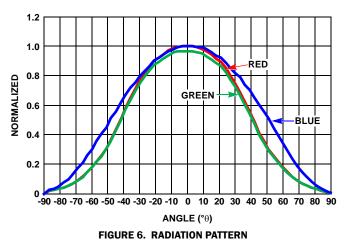


FIGURE 4. I<sup>2</sup>C WRITE CYCLE TIMING

# **Typical Performance Curves**





# **Principles of Operation**

# **Photodiodes and ADC**

The ISL29125 contains three photodiode arrays, which convert light into current. The spectral response for RED, GREEN, and BLUE color ambient intensity sensing is as shown in Figure 2. After light is converted to current during the light to signal process, the current output is converted to a digital count by an on-chip Analog-to-Digital Converter (ADC). The ADC converter resolution is selectable from 4, 8, 12 or 16 bits. The ADC conversion time is inversely proportional to the ADC resolution.

The ADC converter uses an integrating architecture. This conversion method is ideal for converting small signals in the presence of a periodic noise. A 100ms integration time (16-bit mode) for instance, rejects 50Hz and 60Hz power line as well as florescent flicker noise.

The ADC integration time is determined by an internal oscillator and the n-bit (n = 4, 8, 12, 16) counter inside the ADC. A good balancing act of integration time and resolution depends on the application for optimum system performance.

The ADC provides two programmable ranges to dynamically accommodate different lighting conditions. For dim conditions, the ADC can be configured at its high sensitivity (low optical) range. For bright conditions, the ADC can be configured at its low sensitivity (higher optical) range. Note that the effective optical sensitivity of the ISL29125 in terms of counts/ $\mu$ W/cm2 is directly proportional to the ADC integration time.

### **SYNC Mode**

SYNC mode is when B5 at Reg0x1 is set to '1', the INT pin becomes an input pin. This mode is beneficial for some systems which have multiple sensors on  $I^2C$  bus. Once B5 is set, on the rising edge of INT, ADC starts conversion, so that multiples devices would measure at exactly the same time. Yet, to read data out, the system needs to have a different  $I^2C$  address for each sensor or have a multiplexer. Moreover, B5 is set to '0', the INT pin will be asserted whenever the sensor has interrupt trigger.

### **Interrupt Function**

The active low interrupt pin is an open drain pull-down configuration. The interrupt pin serves as an alarm or monitoring function to determine whether the ambient light level exceeds the upper threshold or goes below the lower threshold. It should be noted that the function of ADC conversion continues without stopping after interrupt is asserted. If the user needs to read the ADC count that triggers the interrupt, the reading should be done before the data registers are refreshed by the following conversions. The user can also configure the persistency of the interrupt pin. This reduces the possibility of false triggers, such as noise or sudden spikes in ambient light conditions. An unexpected camera flash, for example, can be ignored by setting the persistency to 8 integration cycles. ISL29125 interrupt modes can be selected at Bit[1:0] at Reg0x03 Table11. User can select Red or Green or Blue to be the interrupt target. An interrupt event (RGBTHF) bit at Reg0x08 is governed by Registers 4 through 7. The user writes a high and low threshold value to these registers and the ISL29125 will issue an interrupt flag if the actual count stored in Registers 0x9 and 0xA for Green or Registers 0xB and 0xC for Red or Register 0xD and 0xE for Blue are outside the user's programmed window. Once ISL29125 issues the interrupt flag, the interrupt status (RGBTHF) bit at Reg0x08 is asserted to logic HIGH and the INT pin goes low. Both the INT pin and the interrupt status bit are automatically cleared at the end of the 8-bit Device Register byte (0x08) transfer. By default (RGBTHF) bit is LOW or it is within the interrupt thresholds window.

# **Power-On Reset**

The Power-On Reset (POR) circuitry protects the internal logic against powering up in the incorrect state. The ISL29125 will power-up into Standby mode after VDD exceeds the POR trigger level and will power-down into Reset mode when VDD drops below the POR trigger level. This bidirectional POR feature protects the device against 'brown-out' failure following a temporary loss of power.

The POR is an important feature because it prevents the ISL29125 from starting to operate with insufficient power supply voltage. The ISL29125 prevents communication to its registers and reduces the likelihood of data corruption on power-up.

# **Serial Interface**

The ISL29125 supports the Inter-Integrated Circuit ( $l^2C$ ) bus data transmission protocol. The  $l^2C$  bus is a two wire serial bidirectional interface consisting of SCL (clock) and SDA (data). Both the wires are connected to the device supply via pull-up resistors. The  $l^2C$  protocol defines any device that sends data onto the bus as a transmitter and the receiving device as the receiver. The device controlling the transfer is a master and the device being controlled is the slave. The transmitting device pulls down the SDA line to transmit a "0" and releases it to transmit a "1". The master always initiates the data transfer, only when the bus is not busy, and provides the clock for both transmit and receive operations. The ISL29125 operates as a slave device in all applications. The serial communication over the  $l^2C$  interface is conducted by sending the most significant bit (MSB) of each byte of data first.

# **Start Condition**

During data transfer, the SDA line must remain stable while the SCL line is HIGH. All I<sup>2</sup>C interface operations must begin with a START condition, which is a HIGH to LOW transition of SDA while SCL is HIGH (refer to Figure 9). The ISL29125 continuously monitors the SDA and SCL lines for the START condition and does not respond to any command until this condition is met (refer to Figure 9). A START condition is ignored during the power-up sequence.

### **Stop Condition**

All I<sup>2</sup>C interface operations must be terminated by a STOP condition, which is a LOW to HIGH transition of SDA while SCL is HIGH (refer to Figure 9). A STOP condition at the end of a

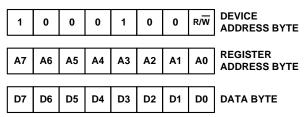
read/write operation places the device in its standby mode. If a stop is issued in the middle of a Data byte, or before 1 full Data byte and ACK is sent, then the serial communication of ISL29125 resets itself without performing the read/write. The contents of the register array are not affected.

### Acknowledge

An acknowledge (ACK) is a software convention used to indicate a successful data transfer. The transmitting device releases the SDA bus after transmitting 8-bits. During the ninth clock cycle, the receiver pulls the SDA line LOW to acknowledge the reception of the eight bits of data (refer to Figure 9). The ISL29125 responds with an ACK after recognition of a START condition followed by a valid Identification Byte, and once again, after successful receipt of an Address Byte. The ISL29125 also responds with an ACK after receiving a Data byte of a write operation. The master must respond with an ACK after receiving a Data byte of a read operation

### **Device Addressing**

Following a START condition, the master must output a Device Address byte. The 7 MSBs of the Device Address byte are known as the device identifier. The device identifier bits of ISL29125 are internally hard-wired as "1000100". The LSB of the Device Address byte is defined as read or write  $(R/\overline{W})$  bit. When this  $R/\overline{W}$  bit is a "1", a read operation is selected and when "0", a write operation is selected (refer to Figure 7). The master generates a START condition followed by Device Address byte 1000100x (x as  $R/\overline{W}$ ) and the ISL29125 compares it with the internal device identifier. Upon a correct comparison, the device outputs an acknowledge (LOW) on the SDA line (refer to Figure 9).





# Write Operation

### **BYTE WRITE**

In a byte write operation, ISL29125 requires the Device Address byte, Register Address byte, and the Data byte. The master starts the communication with a START condition. Upon receipt of the Device Address byte, Register Address byte, and the Data byte, the ISL29125 responds with an acknowledge (ACK). Following the ISL29125 data acknowledge response, the master terminates the transfer by generating a STOP condition. ISL29125 then begins an internal write cycle of the data to the volatile memory. During the internal write cycle, the device inputs are disabled and the SDA line is in a high impedance state, so the device will not respond to any requests from the master (refer to Figure 8).

### **BURST WRITE**

The ISL29125 has a burst write operation, which allows the master to write multiple consecutive bytes from a specific address location. It is initiated in the same manner as the byte write operation, but instead of terminating the write cycle after the first Data byte is transferred, the master can write to the whole register array. After the receipt of each byte, the ISL29125 responds with an acknowledge, and the address is internally incremented by one. The address pointer remains at the last address byte written. When the counter reaches the end of the register address list, it "rolls over" and goes back to the first Register Address.

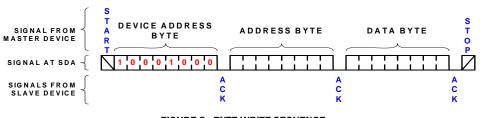


FIGURE 8. BYTE WRITE SEQUENCE

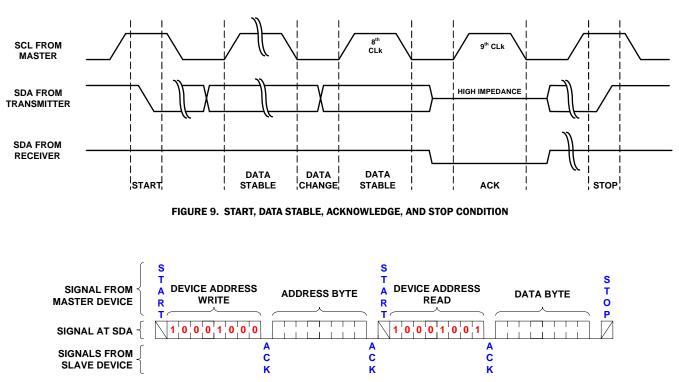


FIGURE 10. BYTE ADDRESS READ SEQUENCE

### **Read Operation**

ISL29125 has two basic read operations: Byte Read and Burst Read.

#### **BYTE READ**

Byte read operations allows the master to access any register location in the ISL29125. The Byte read operation is a two step process. The master issues the START condition and the Device Address byte with the  $R/\overline{W}$  bit set to "0", receives an acknowledge, then issues the Register Address byte. After acknowledging receipt of the register address byte, the master immediately issues another START condition and the Device Address byte with the  $R/\overline{W}$  bit set to "1". This is followed by an acknowledge from the device and then by the 8-bit data word. The master terminates the read operation by not responding with an acknowledge and then issuing a stop condition. Refer to Figure 10.

#### **BURST READ**

Burst read operation is identical to the Byte Read operation. After the first Data byte is transmitted, the master now responds with an acknowledge, indicating it requires additional data. The device continues to output data for each acknowledge received. The master terminates the read operation by not responding with an acknowledge but issuing a STOP condition (refer to Figure 11).

For more information about the  $I^2C$  standard, please consult the Phillips<sup>TM</sup>  $I^2C$  specification documents.

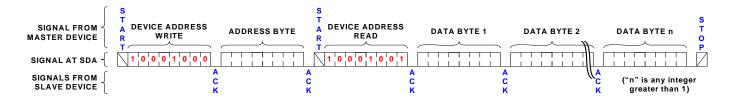


FIGURE 11. BURST READ SEQUENCE

	REGISTE	R ADDRESS				REGISTE	R BITS					
NAME	DEC	HEX	B7	B6	B5	B4	B3	B2	B1	BO	DEFAULT	ACCESS
Device ID	•	0.00	ID[7]	ID[6]	ID[5]	ID[4]	ID[3]	ID[2]	ID[1]	ID[0]	0x7D	RO
Device Reset	0	0x00	ID[7]	ID[6]	ID[5]	ID[4]	ID[3]	ID[2]	ID[1]	ID[0]	NA	wo
<b>CONFIGURATION - 1</b>	1	0x01	RESE	RVED	SYNC	BITS	RNG	MODE[2]	MODE[1]	MODE[0]	0x00	RW
<b>CONFIGURATION - 2</b>	2	0x02	IRCOM	RESERVED	ALSCC[5]	ALSCC[4]	ALSCC[3]	ALSCC[2]	ALSCC[1]	ALSCC[0]	0x00	RW
<b>CONFIGURATION - 3</b>	3	0x03		RESERVED	r.	CONVEN	PRST[1]	PRST[0]	INTSEL[1]	INTSEL[0]	0x00	RW
LOW THRESHOLD - LOW BYTE	4	0x04	THL[7]	THL[6]	THL[5]	THL[4]	THL[3]	THL[2]	THL[1]	THL[0]	0x00	RW
LOW THRESHOLD - HIGH BYTE	5	0x05	THL[15]	THL[14]	THL[13]	THL[12]	THL[11]	THL[10]	THL[9]	THL[8]	0x00	RW
HIGH THRESHOLD - LOW BYTE	6	0x06	THH[7]	THH[6]	THH[5]	THH[4]	THH[3]	THH[2]	THH[1]	THH[0]	0xFF	RW
HIGH THRESHOLD - HIGH BYTE	7	0x07	THH[15]	THH[14]	THH[13]	THH[12]	THH[11]	THH[10]	THH[9]	THH[8]	0xFF	RW
STATUS FLAGS	8	0x08	RESE	RVED	GRBCF[1]	GRBCF[0]	RESERVED	BOUTF	CONVENF	RGBTHF	0x04	RO
GREEN DATA - LOW BYTE	9	0x09	GREEN[7]	GREEN[6]	GREEN[5]	GREEN[4]	GREEN[3]	GREEN[2]	GREEN[1]	GREEN[0]	0x00	RW
GREEN DATA - HIGH BYTE	10	0x0A	GREEN[15]	GREEN[14]	GREEN[13]	GREEN[12]	GREEN[11]	GREEN[10]	GREEN[9]	GREEN[8]	0x00	RW
RED DATA - LOW BYTE	11	0x0B	RED[7]	RED[6]	RED[5]	RED[4]	RED[3]	RED[2]	RED[1]	RED[0]	0x00	RW
RED DATA - HIGH BYTE	12	0x0C	RED[15]	RED[14]	RED[13]	RED[12]	RED[11]	RED[10]	RED[9]	RED[8]	0x00	RW
BLUE DATA - LOW BYTE	13	0x0D	BLUE[7]	BLUE[6]	BLUE[5]	BLUE[4]	BLUE[3]	BLUE[2]	BLUE[1]	BLUE[0]	0x00	RW
BLUE DATA - HIGH BYTE	14	0x0E	BLUE[15]	BLUE[14]	BLUE[13]	BLUE[12]	BLUE[11]	BLUE[10]	BLUE[9]	BLUE[8]	0x00	RW

#### TABLE 1. REGISTER MAP

# **Register Description**

Following are detailed descriptions of the control registers related to the operation of the ISL29125 ambient light sensor device. These registers are accessed by the I<sup>2</sup>C serial interface. For details on the I<sup>2</sup>C interface, refer to "Serial Interface" on page 6.

All the features of the device are controlled by the registers. The ADC data can also be read. The following sections explain the details of each register bit. All RESERVED bits are Intersil used bits ONLY. The value of the reserved bit can change without any notice.

### **Device Register (Address: 0x00)**

TABLE 2.	<b>DEVICE ID</b>	REGISTER	ADDRESS

	REGISTER	ADDRESS		REGISTER BITS								
NAME	DEC	HEX	B7	<b>B6</b>	B5	B4	B3	B2	B1	BO	DEFAULT	ACCESS
Device ID	0	0x00	ID[7]	ID[6]	ID[5]	ID[4]	ID[3]	ID[2]	ID[1]	ID[0]	0x7D	RO
Device Reset	U	0,00	ID[7]	ID[6]	ID[5]	ID[4]	ID[3]	ID[2]	ID[1]	ID[0]	NA	wo

Register 0x00 performs two functions. If Reg 0x00 is in READ ONLY mode then it will be a Device ID. By default, the device ID is 0x7D in hex. Write 46h to register 0x00 in the WRITE ONLY, the device will reset all registers to their default states.

### Configuation-1 Register (Address: 0x01)

#### TABLE 3. CONFIGURATION-1

	REGISTE	R ADDRESS		REGISTER BITS								
NAME	DEC	HEX	B7	B7 B6 B5 B4 B3 B2 B1 B0					DEFAULT	ACCESS		
Configuration-1	1	0x01	RESERVED	RESERVED	SYNC	BITS	RNG	MODE[2]	MODE[1]	MODE[0]	0x00	RW

### **RGB Operating Modes [B2:B0]**

This device has various RGB operating modes. These modes are selected by setting B2:B0 bits in Table 4. The device powers up on a disable mode. All operating modes are in continuous ADC conversion. The following bits are used to enable the operating mode mode

#### TABLE 4. OPERATION MODES

B2:B0	OPERATION
000	Power Down (ADC conversion)
001	GREEN Only
010	RED Only
011	BLUE Only
100	Stand by (No ADC conversion)
101	GREEN/RED/BLUE
110	GREEN/RED
111	GREEN/BLUE

### **RGB Data Sensing Range [B3]**

The Full Scale RGB Range has two different selectable ranges at bit 3. The range determines the ADC resolution (12 bits, and 16 bits). Each range has a maximum allowable lux value. Higher range values offer better resolution and wider lux value.

TABLE	5.	SENSING	RANGES
	υ.	OLITOITTO	INTIGEO

B3	RANGES
0	375 lux
1	10,000 lux

### Configuration-2 Register (Address: 0x02)

# **ADC Resolution [B4]**

ADC's resolution and the number of clock cycles per conversion is determined by this bit in Table 6. Changing the resolution of the ADC, changes the number of clock cycles of the ADC which in turn changes the integration time. Integration time is the period the ADC samples the photodiode current signal for a measurement

#### TABLE 6. ADC RESOLUTIONS

B4	RESOLUTION
0	16 bits
1	12 bits

# RGB Start Synced at INT pin

#### TABLE 7. SYNCED AT INT

B5	OPERATION
0	ADC start at I <sup>2</sup> C write 0x01
1	ADC start at rising INT

SYNC has two different selectable modes at bit 5. B5 sets to 0 then INT pin gets asserted whenever the sensor interrupts. B5 sets to 1 then INT pin becomes input pin. On the rising edge at INT pin, SYNC starts ADC conversion. INT pin set to interrupt mode by default. More information about SYNC at Principle Operation on page 6.

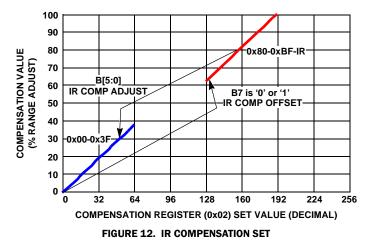
#### TABLE 8. CONFIGURATION-2

NAME	REGISTER	R ADDRESS		REGISTER BITS				DEFAULT	ACCESS			
	DEC	HEX	B7	B6	B5	B4	B3	B2	B1	BO		
Configuration-2	2	0x02	IR-COM	RESERVED	ALSCC[5]	ALSCC[4]	ALSCC[3]	ALSCC[2]	ALSCC[1]	ALSCC[0]	0x00	RW

#### **ACTIVE INFRARED (IR) COMPENSATION**

The device is designed for operation under dark glass cover which significantly attenuates visible light and pass the infrared light without much attenuation. The device has an on chip passive optical filter designed to block (reject) most of the incident Infra Red. In addition, the device provides a programmable active IR compensation which allows fine tuning of residual infrared components from the output which allows optimizing the measurement variation between differing IR-content light sources. B7 is "IR Comp Offset" and B[5:0] is "IR Comp Adjust" which provides means for adjusting IR compensation. B7='0' + B[5:0] is the effective IR compensation from 0 to 63 codes and B7set to '1'+B[5:0] the effective IR compensation is from 106 to 169. Table 9 shows lightweight for each IR compensation bit and Figure 12 is a typical system measure for both IR Comp Adjust and IR Comp Offset. More detail about how to IR compensation, see IR compensation in "Applications Information" on page 13.

Recommended to set BF at register 0x02 to max out IR compensation value. It make High range reach more than 10,000 lux.



B7	B6	B5	B4	B3	B2	B1	BO	LIGHT-WEIGHT
IR-COM	RESERVED	ALSCC[5]	ALSCC[4]	ALSCC[3]	ALSCC[2]	ALSCC[1]	ALSCC[0]	
106		32	16	8	4	2	1	Codes

NOTES:

11. A illuminant is intended to represent typical, domestic, tungsten-filament lighting. Its CCT is about 2856K.

12. D series of illuminants are constructed to represent natural daylight. D65 is used in lab to represent as noon light to test. Its CCT is 6504K.

13. F series of illuminants represent various types of fluorescent lighting. F2 is cool white fluorescent using in lab to test. Its CCT is 4230K.

### Configuration-3 Register (Address: 0x03)

NAME	REGISTE	R ADDRESS				REGISTER	BITS				DEFAULT	ACCESS
	DEC	HEX	B7	B6	B5	B4	B3	B2	B1	BO		
CONFIGURATION-3	3	0x03	RESERVED	RESERVED	RESERVED	CONVEN	PRST[1]	PRST[0]	INTSEL[1]	INTSEL[0]	0x00	RW

#### **INTERRUPT THRESHOLD ASSIGNMENT [B1:0]**

The interrupt status bit (RGBTHF) bit0 at Reg0x08 is a status bit for light intensity detection. The bit is set to logic HIGH when the light intensity crosses the interrupt thresholds window (register address 0x04 - 0x07), and set to logic LOW when its within the interrupt thresholds window. Once the interrupt is triggered, the INT pin goes low and the interrupt status bit goes HIGH until the status bit is polled through the  $I^2C$  read command. Both the INT pin and the interrupt status bit are automatically cleared at the end of the 8-bit Device Register byte (0x08) transfer. Table 11 shows selectable interrupt for the device.

TARI F	11	INTERRUPT	STATUS
INDLE	-	INTERNUTI	314103

B1:0	INTERRUPT STATUS
00	No Interrupt
01	GREEN Interrupt
10	RED Interrupt
11	BLUE Interrupt

#### **INTERRUPT PERSIST CONTROL [B3:2]**

To minimize interrupt events due to 'transient' conditions, an interrupt persistency option is available. IN the event of transient condition an 'X-consecutive' number of interrupt must happen before the interrupt flag and pint ( $\overline{\text{INT}}$ ) pin gets driven low. The interrupt is active-low and remains asserted until the status register (Addr: 0x08) is read to CLEAR the bit(s).

#### TABLE 12. INTERRUPT PERSIST

B3:2	NUMBER OF INTEGRATION CYCLE
00	1
01	2
10	4
11	8

#### **RGB CONVERSION DONE TO INT CONTROL [B4]**

#### TABLE 13.

B4	CONVERSION DONE
0	Disable
1	Enable

# Lower Interrupt Register (Address: 0x04 and 0x05) and Higher Interrupt Register (Address: 0x06 and 0x07)

TABLE 14. CONFIGURATION-3
PEGISTER BITS

NAME	REGISTER ADDRESS		REGISTER BITS								DEFAULT	ACCESS
	DEC	HEX	B7	B6	B5	B4	B3	B2	B1	BO		
Low Threshold-Low byte	4	0x04	THL[7]	THL[6]	THL[5]	THL[4]	THL[3]	THL[2]	THL[1]	THL[0]	0x00	RW
Low Threshold- High byte	5	0x05	THH[7]	THH[6]	THH[5]	THH[4]	THH[3]	THH[2]	THH[1]	THH[0]	0x00	RW
High Threshold- Low byte	6	0x06	THL[7]	THL[6]	THL[5]	THL[4]	THL[3]	THL[2]	THL[1]	THL[0]	OxFF	RW
High Threshold-High byte	7	0x07	THH[7]	THH[6]	THH[5]	THH[4]	THH[3]	THH[2]	THH[1]	THH[0]	OxFF	RW

# Interrupt Threshold (Reg 0x4, Reg0x5, Reg0x6 and Reg0x7)

The interrupt threshold level is a 16-bit number (Low Threshold-1 and Low Threshold-2). The lower interrupt threshold registers are used to set the lower trigger point for interrupt generation. If the ALS value crosses below or is equal to the lower threshold, an interrupt is asserted on the interrupt pin (LOW) and the interrupt status bit (HIGH). Registers Low Threshold-1 (0x04 or 0x6) and Low Threshold-2 (0x05 or 0x7) provide the low and high bytes, respectively, of the lower interrupt threshold. The interrupt threshold registers default to 0x00 upon power up. The user can also configure the persistency for the interrupt pin. This reduces the possibility of false triggers, such as noise or sudden spikes in ambient light conditions or an unexpected camera flash, for example, can be ignored by setting the persistency to 8 integration cycles.

# Status Flag Register (Address: 0x08)

#### TABLE 15. STATUS FLAG REGISTER

NAME		ster Ress		REGISTER BITS							DEFAULT	ACCESS
Status Flag	DEC	HEX	B7	<b>B6</b>	B5	B4	B3	B2	B1	BO		
	8	0x08	RESERVED	RESERVED	RGBCF[1]	RGBCF[0]	RESERVED	BOUTF	CONVENF	RGBTHF	0x04	RO

#### **RGBTHF** [B0]

This is the status bit of the interrupt. The bit is set to logic high when the interrupt thresholds have been triggered (out of threshold window), and logic low when not yet triggered. Once activated and the interrupt is triggered, the INT pin goes low and the interrupt status bit goes high until the status bit is polled through the  $I^2C$  read command. Both the INT output and the interrupt status bit are automatically cleared at the end of the 8-bit (00h) command register transfer

#### TABLE 16. INTERRUPT FLAG

BO	OPERATION
0	Interrupt is cleared or not triggered yet
1	Interrupt is triggered

#### CONVENF [B1]

This is the status bit of conversion. The bit is set to logic high when the conversion have been completed, and logic low when the conversion is not done or not conversion.

B1	OPERATION						
0	Still convert or cleared						
1	Conversion completed						

#### BOUTF [B2]

Bit2 on register address 0x08 is a status bit for brownout condition (BOUT). The default value of this bit is HIGH, BOUT = 1, during the initial power up. This indicates the device may possibly have gone through a brownout condition. Therefore, the status bit should be reset to LOW, BOUT = 0, by an I<sup>2</sup>C write command during the initial configuration of the device. The default register value is 0x04 at power-on.

#### TABLE 18. BROWNOUT FLAG

B2	OPERATION
0	No Brownout
1	Power down or Brownout occurred

#### RGBCF [B5:B4]

B[5:4] are flag bits to display either Red or Green or Blue is under conversion process at Table 19.

B5:4	RGB UNDER CONVERSION
00	No Operation
01	GREEN
10	RED
11	BLUE

### Data Register (Address: 0x09,0x0A,0xB,0xC,0xD and 0xE)

NAME	REGISTE	R ADDRESS		DEFAULT	ACCESS							
	DEC	HEX	B7	B6	B5	B4	B3	B2	B1	BO	1	
GREEN data-Low byte	9	0x09	GREEN[7]	GREEN[6]	GREEN[5]	GREEN[4]	GREEN[3]	GREEN[2]	GREEN[1]	GREEN[0]	0x00	RW
GREEN data-High byte	10	0x0A	GREEN[15]	GREEN[14]	GREEN[13]	GREEN[12]	GREEN[11]	GREEN[10]	GREEN[9]	GREEN[8]	0x00	RW
RED data-Low byte	11	0x0B	RED[7]	RED[6]	RED[5]	RED[4]	RED[3]	RED[2]	RED[1]	RED[0]	0x00	RW
RED data-High byte	12	0x0C	RED15]	RED[14]	RED[13]	RED[12]	RED[11]	RED[10]	RED[9]	RED[8]	0x00	RW
RED data-Low byte	13	0x0D	BLUE[7]	BLUE[6]	BLUE[5]	BLUE[4]	BLUE[3]	BLUE[2]	BLUE[1]	RED[0]	0x00	RW
RED data-High byte	14	0x0E	BLUE[15]	BLUE[14]	BLUE[13]	BLUE[12]	BLUE[11]	BLUE[10]	BLUE[9]	RED[8]	0x00	RW

**TABLE 20. CONFIGURATION-3** 

The ISL29125 has two 8-bit read-only registers to hold the higher and lower byte of the ADC value. The lower byte and higher bytes are accessed at address respectively. For 16-bit resolution, the data is from D0 to D15; for 12-bit resolution, the data is from D0 to D11. The registers are refreshed after every conversion cycle. The default register value is 0x00 at power-on. Because all the register are double buffered the data is always valid on the data registers.

# **Applications Information**

Below is a plot of the 1931 standard normalized spectral response of various types of light sources for reference.

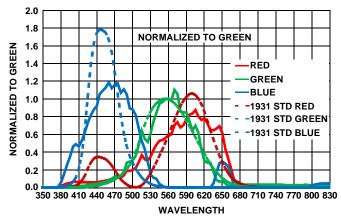


FIGURE 13. 1931 STANDARD NORMALIZED SPECTRAL RESPONSE OF LIGHT SOURCES

### System Compensation and RGB to XYZ Transform (Chroma Meter)

The accuracy of the RGB sensor is extremely sensitive to the opto-mechanical design of the system in which it resides. The compensation setting and calculation of RGB to XYZ transform should be characterized within that environment with as many standard illuminants as possible. A minimal recommended set would include A, F2 and D65 illuminants (see Notes 11, 12, 13 and "References" on page 15 about IEC 1931, Planckian locus and standard illuminants). The two most important opto-mechnical features are FOV (field of view FWHM) and

optical filters as example of tinted cell phone glass through which the sensor will detect the ambient lighting. With the combination of the FOV and a large sample for the filter (30x30mm) it is possible to determine the best compensation and XYZ transform coefficients. It is also possible to project the accuracy of the measurement system.

### $\textbf{RGB} \rightarrow \textbf{XYZ} \text{ TRANSFORM}$

Once the proper compensation setting is determined measure the RGB values of the various illuminates at this value. Calculate the RGB to XYZ transform coefficients based on the measured result against appropriate Chroma Meter Standard (using x and y values). Refer to <u>AN1911</u>.

$$\begin{array}{c} X \\ Y \\ Z \end{array} = \begin{bmatrix} C_{XR} & C_{XG} & C_{XB} \\ C_{YR} & C_{YG} & C_{YB} \\ C_{ZR} & C_{ZG} & C_{ZB} \end{bmatrix} \times \begin{bmatrix} R \\ G \\ B \end{bmatrix}$$
 (EQ. 1)

X, Y, and Z are in the IEC system which specifies the color and brightness of a particular homogeneous visual stimulus.

R, G, and B are digital output from the sensor.

Cs are coefficients. These coefficients will be changed respectively depending on the system setup.

#### COMPENSATION

The compensation adjustment is used to balance the various illuminates of interest (A, F2 and D65 recommended) such that the value measured at the same power level (measured with a Lux meter) is the closed value. Since the compensation adjustment is piecewise linear the proper setting can be

determined by extrapolating from a pair of measurements and calculating the closest intersection of the sources of interest.

The Configuration register (Reg 0x02[7:0]) allows coarse tuning B7 and fine tuning (B[5:0] of the residual infrared component from the ALS output.

The recommended procedure for determining ALS IR compensation is as follows:

- Illuminate the ISL29125 based design configuration with a no IR F2 light source. Record the ALS measurement and the Lux level.
- Illuminate the device with A, and D65 with heavy IR and the F2 light sources. Take an ALS measurement and Lux level measurement.
- It really depend on the system setup in order to adjust the Configuration register (Reg 0x02, B7 and B[5:0]) to compensate for the IR contribution.
- Repeat steps above until the IR light source contribution to the ALS measurement is under 10 percent assuming no change in Lux level due to IR light source.

Figure 14 is an example shows how to calculate the compensation for varying level of infrared components such as A, F2 and D65 (see Notes 11, 12 and 13). With compensation adjustment from 0% to 100%. The crossing point is the IR compensation value which makes tighter variation of varying level of infrared components. This setup system is sensor without IR tinted glass and illuminates with 3 different light sources. Since it is not under IR tinted glass, then reg0x2 setups like b7 = '0' and B[5:0] is at about 25% compensation adjust(%/range) which means about 40 codes.





# **Calculating Lux**

Y-coordinate is Ev measured in lux. The data can be converted to lux by using an equation. There are two different data sensing ranges (375 lux and 10,000 lux) and also two different resolution selections (16 bits and 12 bits) on this device. Equation 2 is dependent on both these parameters.

$$Ev = Y = (CYRxRed + CYGxGreen + CYBxBlue)xRange$$

### **Noise Rejection**

Electrical AC power worldwide is distributed at either 50Hz or 60Hz. Artificial light sources vary in intensity at the AC power frequencies. The undesired interference frequencies are infused on the electrical signals. This variation is one of the main sources of noise for the light sensors. Integrating type ADC's have excellent noise-rejection characteristics for periodic noise sources whose frequency is an integer multiple of the conversion rate. By setting the sensor's integration time to an integer multiple of periodic noise signal, the performance of an ambient light sensor can be improved greatly in the presence of noise. In order to reject the AC noise, the integration time of the sensor must to adjusted to match the AC noise cycle. For instance, a 60Hz AC unwanted signal's sum from 0ms to k\*16.66ms  $(k = 1, 2...k_i)$  is zero. Similarly, setting the device's integration time to be an integer multiple of the periodic noise signal greatly improves the light sensor output signal in the presence of noise.

# **Digital Inputs and Termination**

The ISL29125 digital inputs are guaranteed to CMOS levels. The internal register is updated on the rising edge of the clock. To minimize reflections, proper termination should be implemented. If the lines driving the clock and the digital inputs are  $50\Omega$  lines, then  $50\Omega$  termination resistors should be placed as close to the sensor inputs as possible, connected to the digital ground plane (if separate grounds are used).

# **Temperature Coefficient**

The limits stated for temperature coefficient (Tempco) are governed by the method of measurement. The overwhelming standard for specifying the temperature drift of a reference is to measure the reference voltage at two temperatures, take the total variation, ( $V_{HIGH} - V_{LOW}$ ), and divide by the temperature extremes of measurement ( $T_{HIGH} - T_{LOW}$ ). The result is divided by the nominal reference voltage (at T = +25 °C) and multiplied by 106 to yield ppm/°C. This is the "Box" method for specifying temperature coefficient.

# Layout and Board Mounting Considerations

# **Suggested PCB Footprint**

It is important that users check <u>TB477</u> "Surface Mount Assembly Guidelines for Optical Dual Flat Pack No Lead (ODFN) Package" before starting ODFN product board mounting.

# **Board Mounting**

For applications requiring the light measurement, the board mounting location should be reviewed. The device uses an Optical Dual Flat Pack No Lead (ODFN) package, which subjects the die to mild stresses when the printed circuit (PC) board is heated and cooled, which slightly changes the shape. Because of these die stresses, placing the device in areas subject to slight twisting can cause degradation of reference voltage accuracy. It is normally best to place the device near the edge of a board, or on the shortest side, because the axis of bending is most limited in that location.

### Layout

The ISL29125 is relatively insensitive to layout. Like other I<sup>2</sup>C devices, it is intended to provide excellent performance even in significantly noisy environments. There are only a few considerations that will ensure best performance.

Route the supply and I<sup>2</sup>C traces as far as possible from all sources of noise. Use two power-supply decoupling capacitors,  $\mu$ F and  $0.1\mu$ F, placed close to the device.

# Soldering

Convection heating is recommended for reflow soldering; directinfrared heating is not recommended. The plastic ODFN package does not require a custom reflow soldering profile, and is qualified to +260°C. A standard reflow soldering profile with a +260°C maximum is recommended.

# **Typical Circuit**

A typical application for the ISL29125 is shown in Figure 15. The ISL29125's I<sup>2</sup>C address is internally hard-wired as 1000100. The device can be tied onto a system's I<sup>2</sup>C bus together with other I<sup>2</sup>C compliant devices.

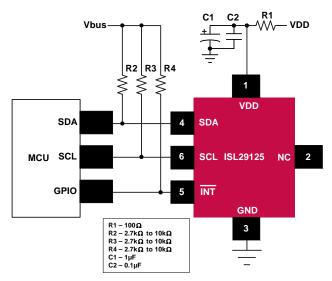


FIGURE 15. ISL29125 TYPICAL CIRCUIT

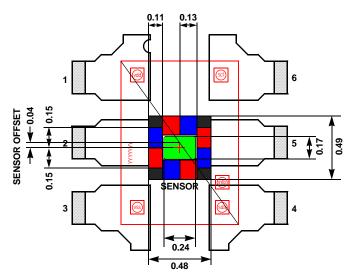


FIGURE 16. 6 LD ODFN SENSOR LOCATION OUTLINE

# References

- [1] Standard illuminants
- [2] Planckian locus approximation
- [3] CIE 1931 2°, XYZ CMFs modified by Judd (1951) and Vos (1978)

# **Revision History**

The revision history provided is for informational purposes only and is believed to be accurate, but not warranted. Please go to web to make sure you have the latest revision.

DATE	REVISION	CHANGE
January 24, 2013	FN8424.2	Page 2, Ordering Information table: Changed Evaluation Board part # from: ISL29125IROZ-EVALZ to: ISL29125EVAL1Z Page 9 - added Device Reset row to Tables 1 and 2.
December 23, 2013	FN8424.1	Added Related Literature on page 1. Updated "Interrupt Function" on page 6. Edited last two rows in Table 20 on page 13. Changed RED to BLUE and Register DEC column from 11 and 12 to 13 and 14.
November 20, 2013	FN8424.0	Initial Release

# **About Intersil**

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For the most updated datasheet, application notes, related documentation and related parts, please see the respective product information page found at <u>www.intersil.com</u>. You may report errors or suggestions for improving this datasheet by visiting <u>www.intersil.com/en/support/ask-an-expert.html</u>. Reliability reports are also available from our website at <u>http://www.intersil.com/en/support/qualandreliability.html#reliability</u>.

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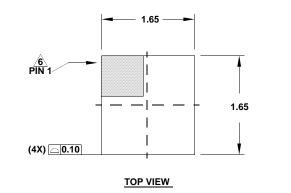
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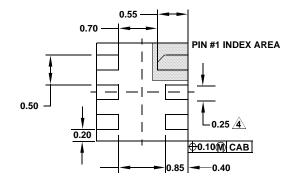
For information regarding Intersil Corporation and its products, see www.intersil.com

# **Package Outline Drawing**

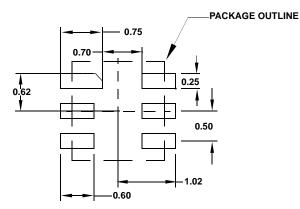
# L6.1.65x1.65

6 LEAD OPTICAL DUAL FLAT NO-LEAD PLASTIC PACKAGE (ODFN) Rev 1, 4/13

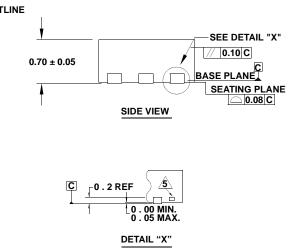




#### BOTTOM VIEW



TYPICAL RECOMMENDED LAND PATTERN



NOTES:

- 1. Dimensions are in millimeters. Dimensions in ( ) for Reference Only.
- 2. Dimensioning and tolerancing conform to ASME Y14.5m-1994.
- 3. Unless otherwise specified, tolerance : Decimal  $\pm 0.05$
- A Dimension applies to the metallized terminal and is measured between 0.15mm and 0.30mm from the terminal tip.
- 5. Tiebar shown (if present) is a non-functional feature.
- 6. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.